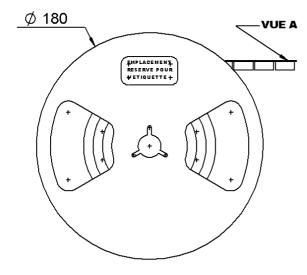
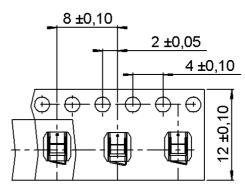
REEL 100

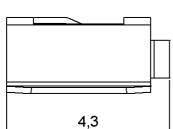
R107.003.010

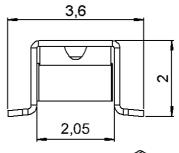
Series: UMP

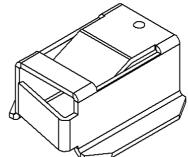




VUE A / VIEW A







SCALE: 1/1

All dimensions are in mm.



COMPONENTS	MATERIALS	PLATINGS (μm)
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS -	BERYLLIUM COPPER	GOLD 0.2 OVER NICKEL 2

Issue: 0415 A



REEL 100

R107.003.010

Series: UMP

PACKAGING

Standard	Unit	Other
100	'W' option	Contact us

SPECIFICATION

ELECTRICAL CHARACTERISTICS

 $\begin{array}{ccc} \text{Impedance} & & \textbf{50} \;\; \Omega \\ \text{Frequency} & & \textbf{0-6} \;\; \text{GHz} \end{array}$

VSWR 1.05 + 0.030 x F(GHz) Maxi

Insertion loss \mathbf{NA} $\sqrt{F(GHz)}$ dB Maxi RF leakage - (\mathbf{NA} - F(GHz)) dB Maxi

Voltage rating 100 Veff Maxi Dielectric withstanding voltage Insulation resistance 1000 M Ω mini

ENVIRONMENTAL

Operating temperature -40/+125 ° C

Hermetic seal **NA** Atm.cm3/s

Panel leakage NA

OTHERS CHARACTERISTICS

Assembly instruction

Others:

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end
Axial force – Opposite end
Torque

NA N mini
NA N mini
NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 100 Cycles mini

Weight **0.035** g

Issue: 0415 A



R107.003.010

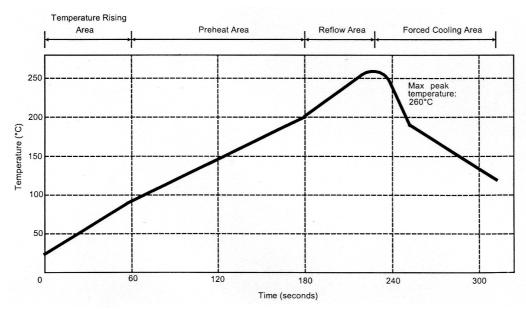
REEL 100

Series: UMP

SOLDER PROCEDURE OF UMP RECEPTACLE IN INDUSTRIAL ENVIRONMENT

- 1. Deposit solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
 - We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. A video camera is recommended for positioning of the component. Adhesive agents must not be used on the receptacle.
- 3. This process of soldering has been tested with convection oven. Below please find, the typical profile to use.
- 4. The cleaning of printed circuit boards is not obliged.
- 5. Verification of solder joints and position of the component by visual inspection.

NOTE : THE UMP RECEPTACLE AND THE UMP PLUG MUST NOT BE MATED BEFORE COMPLETION OF THIS PROCEDURE.



Parmeter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

Issue: 0415 A

In the effort to improve our products, we reserve the right to make changes judged to be

necessary.



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REEL 100

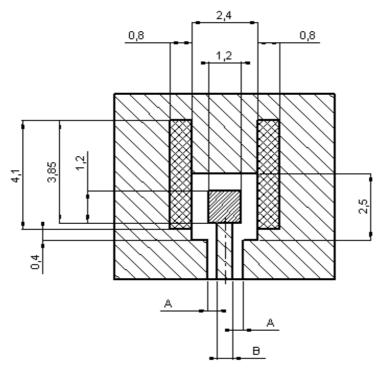
Series: UMP

UMP SERIES INFORMATION

PCB

COPLANAR LINE

Ground and signal are on the same side The material of PCB is glass is glass-epoxy Composite.



Sold over nickel for solder paste

Gold over nickel contact area free of any surface contaminant

Ground + varnish

APPLICATION 75Ω

WITH B = 0.55mm

	PCB thickness (mm)	Coplanar ligne A (mm)
ĺ	0,8	0,57
	1,0	0,45
	1,2	0,41
	1,6	0,37

APPLICATION 50Ω

WITH B = 1,2mm

,	
PCB thickness (mm)	Coplanar ligne A (mm)
0,8	0,183
1,0	0,190
1,2	0,195
1,6	0,20

Issue: 0415 A

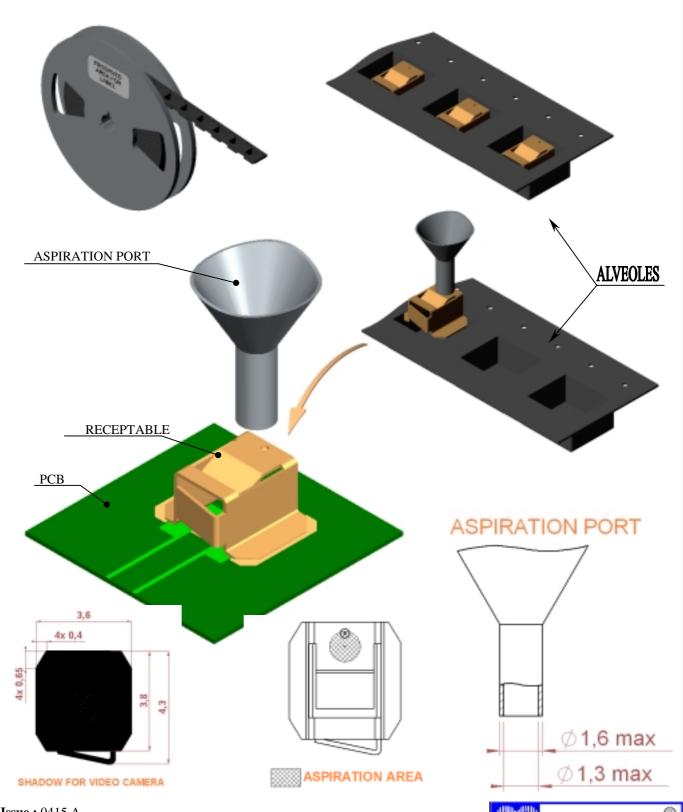


REEL 100

R107.003.010

Series: UMP

UMP SERIES INFORMATION



Issue: 0415 A

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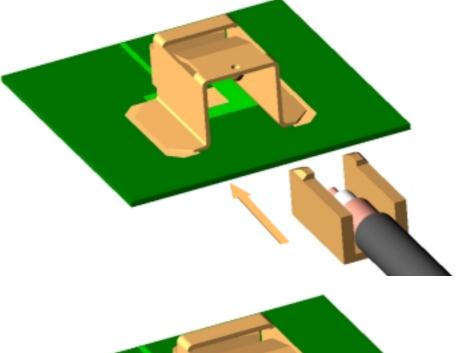
necessary

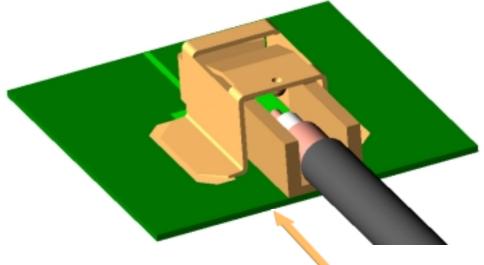
REEL 100

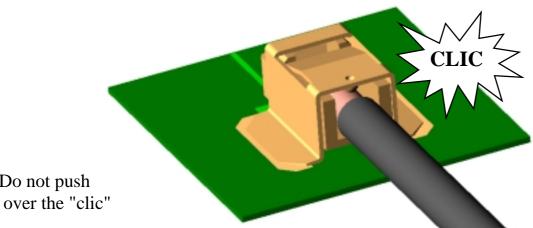
Series: UMP

R107.003.010

UMP CONNECTING NOTE







Issue: 0415 A

Do not push

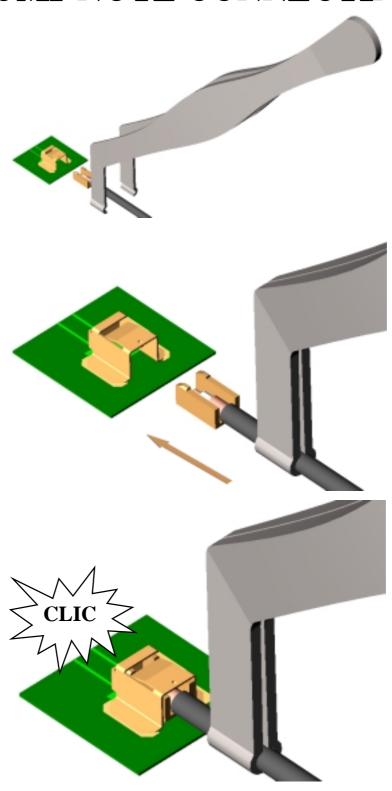


R107.003.010

REEL 100

Series: UMP

UMP NOTE CONNECTING



Do not push over the «clic »

Issue: 0415 A

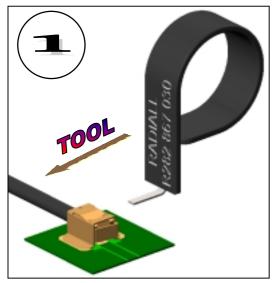


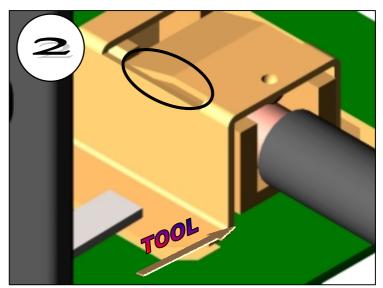
REEL 100

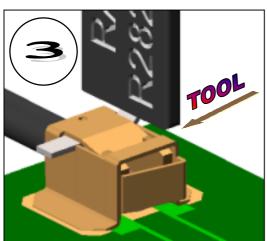
R107.003.010

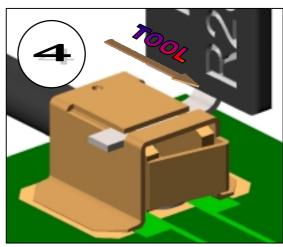
Series: UMP

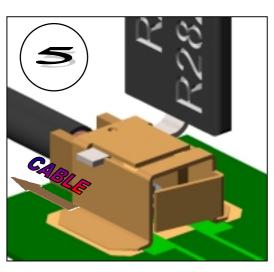
UMP DISCONNECTING NOTE

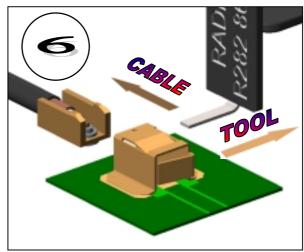












Issue: 0415 A

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